

2SK2570

Silicon N Channel MOS FET Low Frequency Power Switching

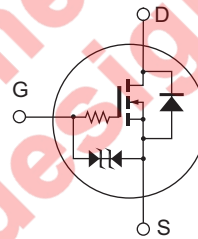
REJ03G1019-0200
(Previous: ADE-208-574)
Rev.2.00
Sep 07, 2005

Features

- Low on-resistance
 $R_{DS(on)} = 0.8 \Omega$ typ. ($V_{GS} = 4 \text{ V}$, $I_D = 100 \text{ mA}$)
- 2.5 V gate drive devices.
- Small package (MPAK)

Outline

RENESAS Package code: PLSP0003ZB-A
(Package name: MPAK)



1. Source
2. Gate
3. Drain

Note: Marking is "ZL—"

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	20	V
Gate to source voltage	V_{GSS}	± 10	V
Drain current	I_D	0.2	A
Drain peak current	$I_{D(pulse)}^{*1}$	0.4	A
Channel dissipation	Pch	150	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note: 1. PW $\leq 10 \mu s$, duty cycle $\leq 1 \%$

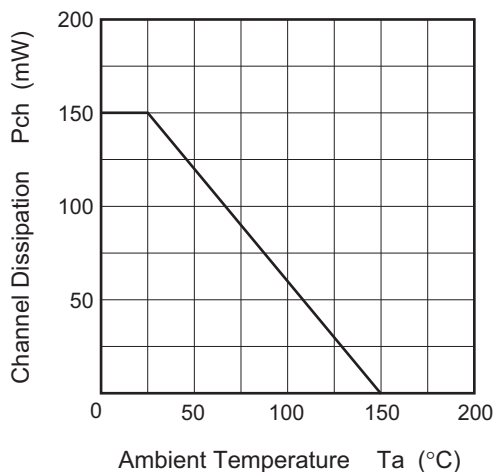
Electrical Characteristics

(Ta = 25°C)

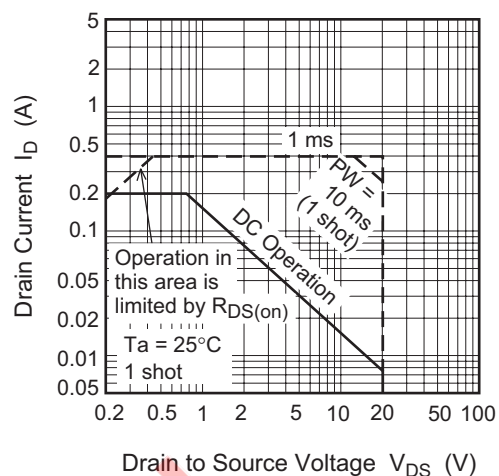
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	20	—	—	V	$I_D = 10 \mu A$, $V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	± 10	—	—	V	$I_G = \pm 100 \mu A$, $V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1.0	μA	$V_{DS} = 20 V$, $V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 5.0	μA	$V_{GS} = \pm 6.5 V$, $V_{DS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	0.5	—	1.5	V	$I_D = 10 \mu A$, $V_{DS} = 5 V$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.8	1.1	Ω	$I_D = 100 mA$, $V_{GS} = 4 V^{*2}$
		—	1.3	2.2	Ω	$I_D = 40 mA$, $V_{GS} = 2.5 V^{*2}$
Forward transfer admittance	$ y_{fs} $	0.22	0.35	—	S	$I_D = 100 mA$, $V_{DS} = 10 V^{*2}$
Input capacitance	C_{iss}	—	45	—	pF	$V_{DS} = 10 V$, $V_{GS} = 0$, $f = 1 MHz$
Output capacitance	C_{oss}	—	33	—	pF	
Reverse transfer capacitance	C_{rss}	—	9.6	—	pF	
Turn-on delay time	$t_{d(on)}$	—	20	—	ns	$V_{GS} = 5 V$, $I_D = 100 mA$, $R_L = 100 \Omega$
Rise time	t_r	—	60	—	ns	
Turn-off delay time	$t_{d(off)}$	—	240	—	ns	
Fall time	t_f	—	140	—	ns	

Notes: 2. Pulse test

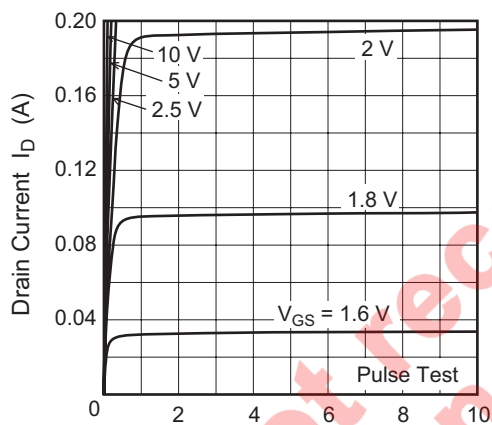
Maximum Channel Dissipation Curve



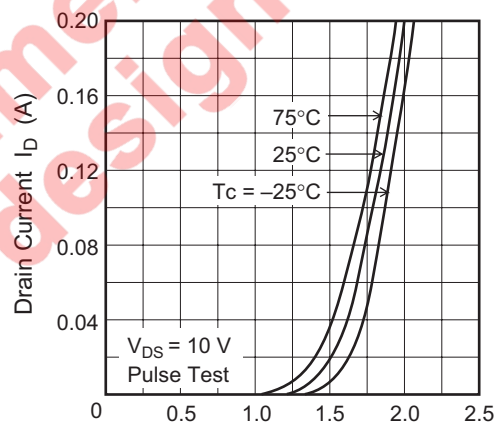
Maximum Safe Operation Area



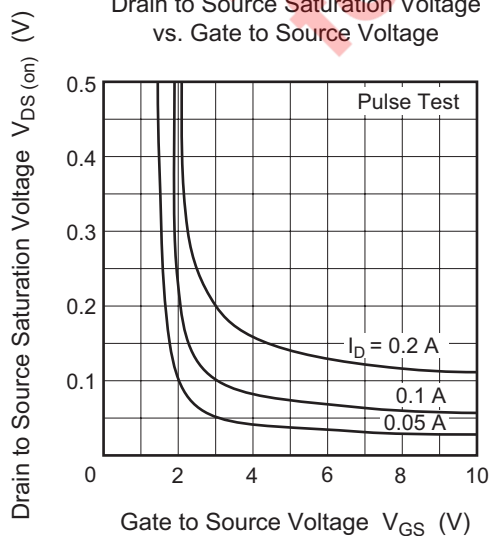
Typical Output Characteristics



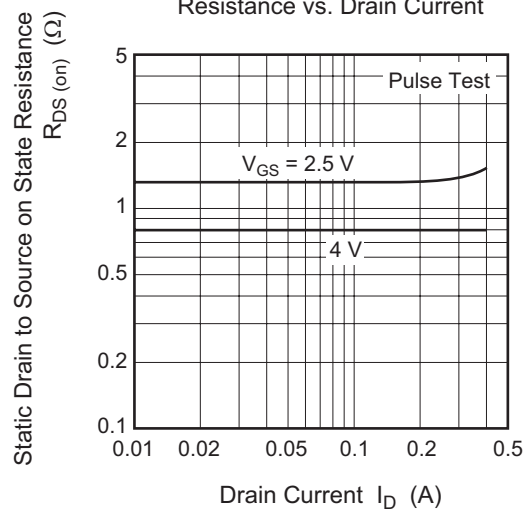
Typical Transfer Characteristics



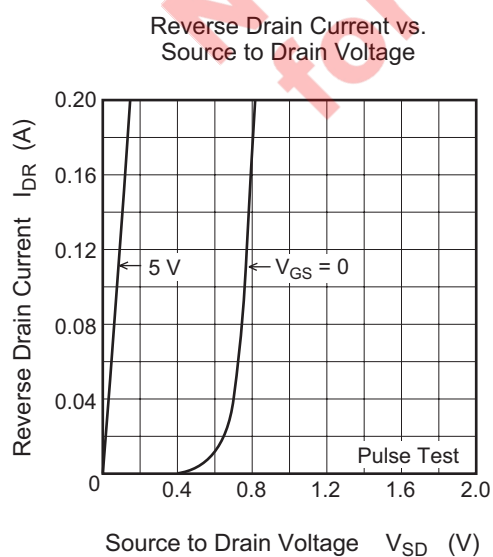
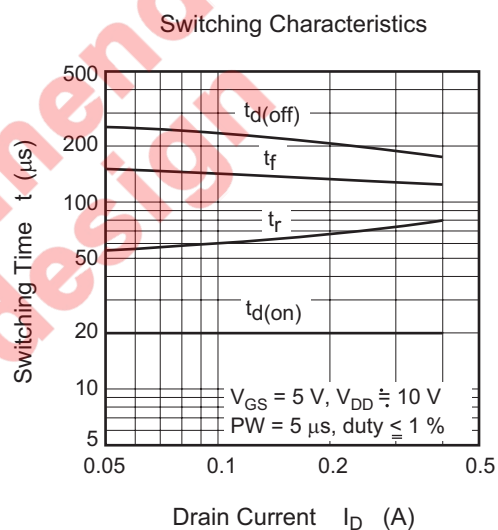
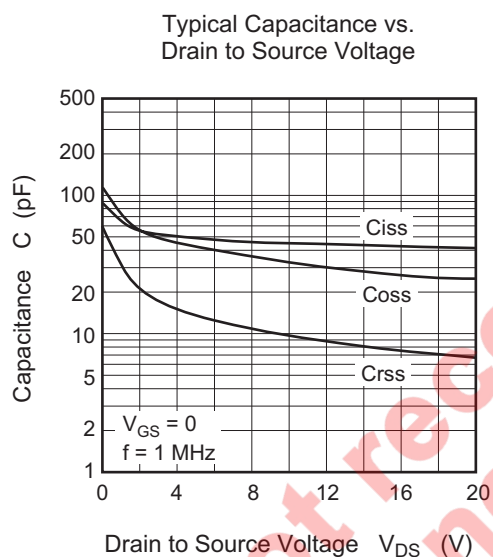
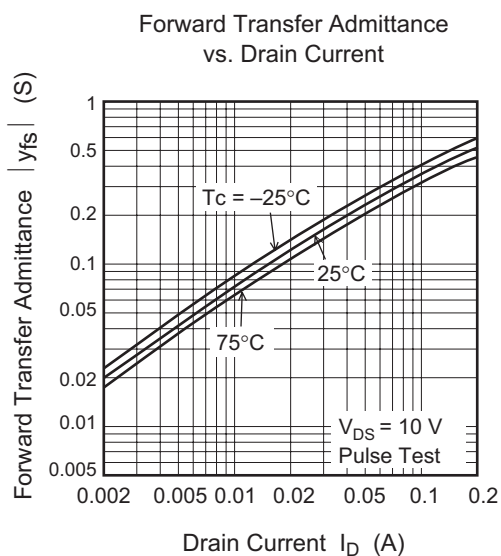
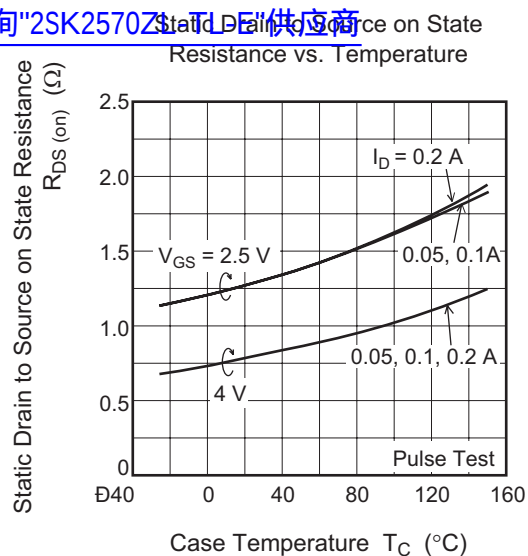
Drain to Source Saturation Voltage vs. Gate to Source Voltage



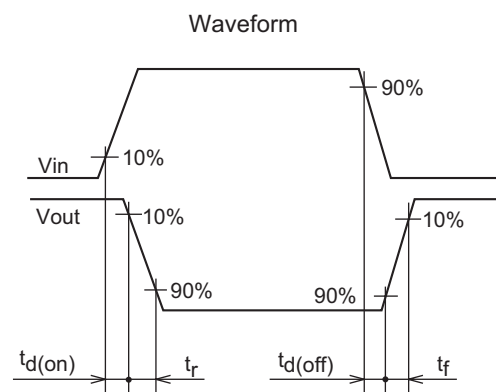
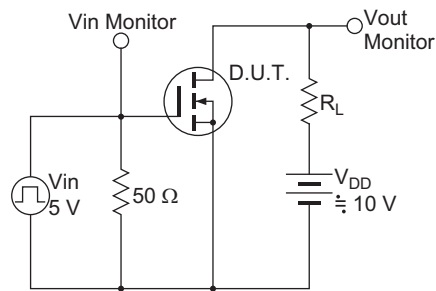
Static Drain to Source on State Resistance vs. Drain Current



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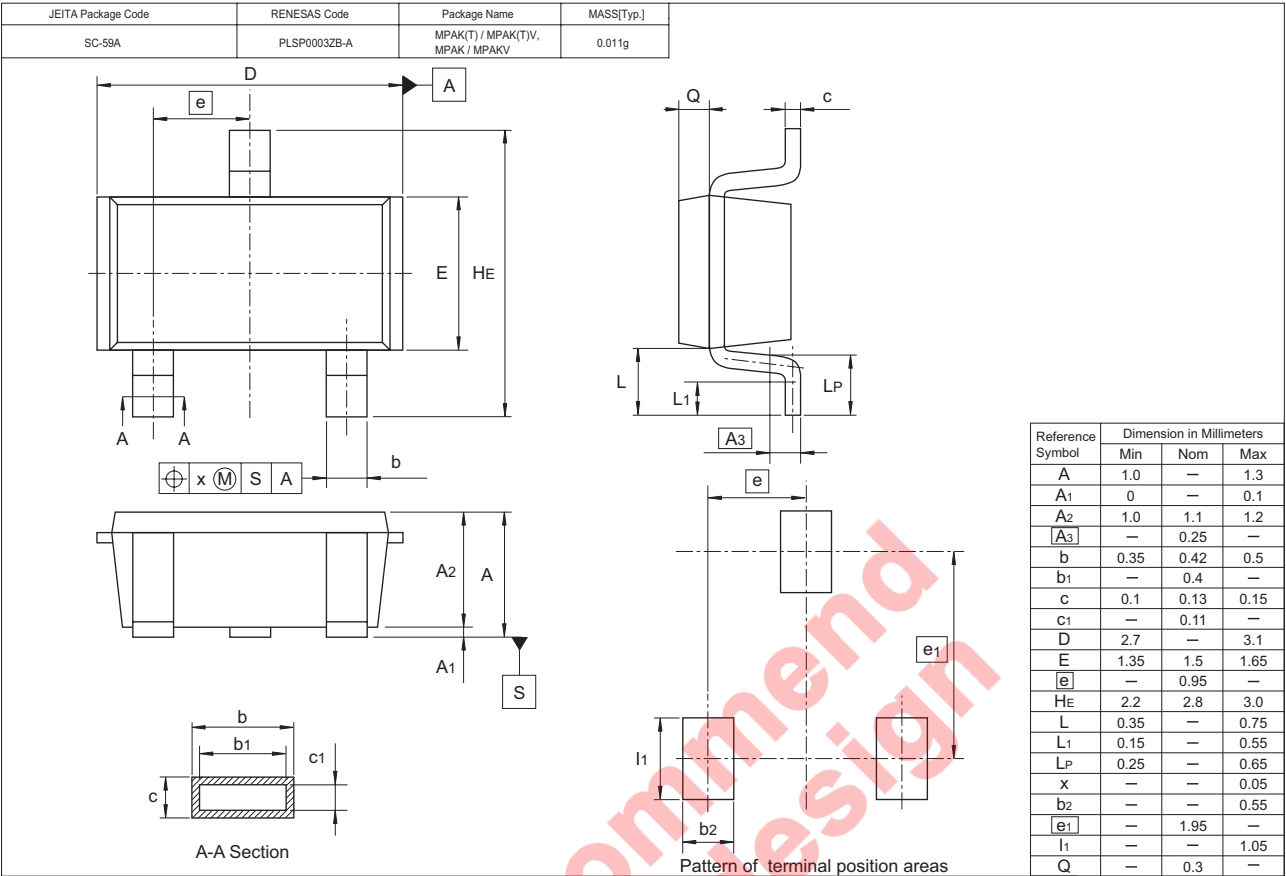


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Not recommend
for new design

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Part Name	Quantity	Shipping Container
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Renesas Technology Hong Kong Ltd.

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Renesas Technology Taiwan Co., Ltd.

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Tel: <82> 2-796-3115, Fax: <82> 2-796-2145

Renesas Technology Malaysia Sdn. Bhd.

Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510